

PRM2R9N10CT

PFC Device Corporation

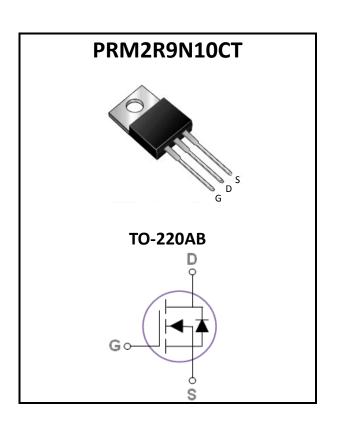
100V Single N-Channel MOSFET

Major ratings and characteristics

Characteristics	Values	Units
V_{DS}	100	٧
$I_D^6 (T_C=25^{\circ}C)$	233	Α
Max. R _{DS(ON)} @V _{GS} =10V	2.9	mΩ
T _J Operating Junction Temperature	-55 to +150	°C

General Description

The N-Channel enhancement mode power field effect transistor is using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. The device is well suited for high efficiency fast switching applications.



Typical Applications

- Charger Adapter
- Power Tools
- LED Lighting

Features

- Max. $R_{DS(ON)}=2.9m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- 100% E_{AS} Guaranteed
- Green Device Available

1. Characteristics

Maximum Ratings Characteristics

($T_A = 25$ °C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
l _D ⁵	Drain Current – Continuous (T _C =25°C)	233	Α
ID	Drain Current – Continuous (T _C =100°C)	147	Α
I _D ⁶	Drain Current – Continuous (T _C =25°C)	60	Α
I _{DM}	Drain Current – Pulsed ¹	240	Α
E _{AS}	Single Pulse Avalanche Energy ²	273	mJ
I _{AS}	Single Pulse Avalanche Current ²	36	Α
Ь	Power Dissipation (T _C =25°C)	284	W
P _D	Power Dissipation – Derate above 25°C	2.3	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient		60	°C/W
$R_{ heta JC}$	Thermal Resistance Junction to Case		0.44	°C/W



Version 4.0 2 / 8

Electrical Characteristics

($T_J = 25$ °C unless otherwise specified)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100			V
	V _{DS} =100V, V _{GS} =0V, T _J =25°C			1	uA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =100°C			100	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V, V_{DS}=0V$			±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A		2.4	2.9	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=250uA$	2.0	2.8	4.0	V
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A		80		S

Dynamic and switching Characteristics

	<u> </u>					
Q_{g}	Total Gate Charge ^{3, 4}	V _{DS} =50V, V _{GS} =10V, I _D =20A		107		
Q_gs	Gate-Source Charge ^{3, 4}			39		nC
Q_gd	Gate-Drain Charge ^{3, 4}			12		
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}			28		
T_r	Turn-On Rise Time ^{3, 4}	V_{DD} =50V, V_{GS} =10V, R_{G} =10 Ω		45		ne
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}	I _D =20A		54		ns
T_f	Turn-Off Fall Time ^{3, 4}		-	23		
C_{iss}	Input Capacitance		-	7384	1	
C_{oss}	Output Capacitance	V _{DS} =50V, V _{GS} =0V, f=1MHz		1184		pF
C_{rss}	Reverse Transfer Capacitance		-	40		
R_{g}	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.2		Ω

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	V _{GS} =0V, I _S =20A	 	1.2	V
t _{rr}	Reverse Recovery Time	1 201 di/dt 1001/up	 85	-	ns
Q_{rr}	Reverse Recovery Charge	I _S =20A, di/dt=100A/us	 151		nC

Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. VDD=50V, VGS=10V, L=0.4mH, RG=25 Ω , Starting TJ=25 $^{\circ}$ C
- 3. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.
- 5. Silicon limited
- 6. Package limited.

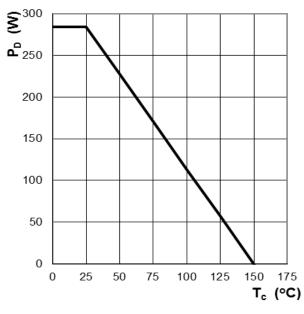


Version 4.0 3 / 8

2. Characteristics Curves

Ratings and Characteristics Curves

(T_A = 25°C unless otherwise specified)



200 100 25 50 75 100 125 150 175 T_c (°C)

Figure 1: Power Dissipation

Figure 2: Continuous Drain Current vs. T_C

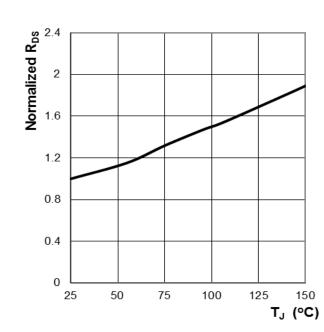


Figure 3: Normalized R_{DS(ON)} vs. T_J

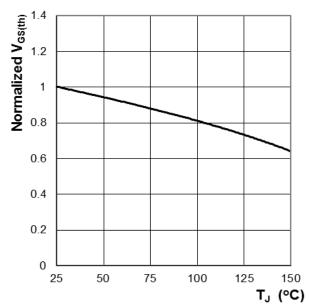


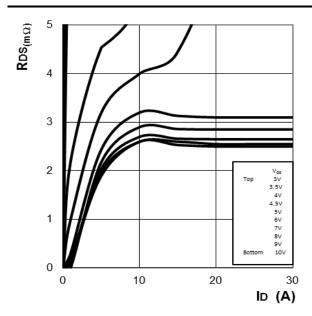
Figure 4: Normalized Vth vs. TJ



Version 4.0 4 / 8

Ratings and Characteristics Curves

($T_A = 25^{\circ}$ C unless otherwise specified)



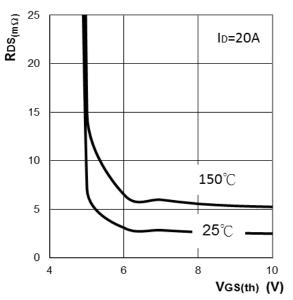
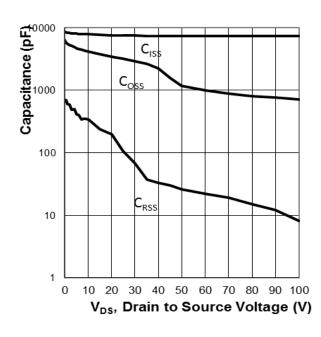


Figure 5: RDS(ON) vs. Drain Current and Gate Voltage

Figure 6: RDS(ON) vs. Gate Voltage



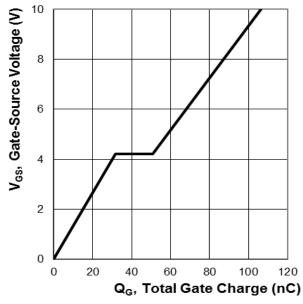


Figure 7: Typ. Capacitance Characteristics

Figure 8: Typ. Gate Charge Characteristics



Version 4.0 5 / 8

Ratings and Characteristics Curves

($T_A = 25^{\circ}C$ unless otherwise specified)

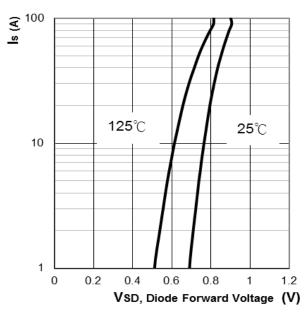


Figure 9: Body Diode Characters

Figure 10: Maximum Safe Operation Area

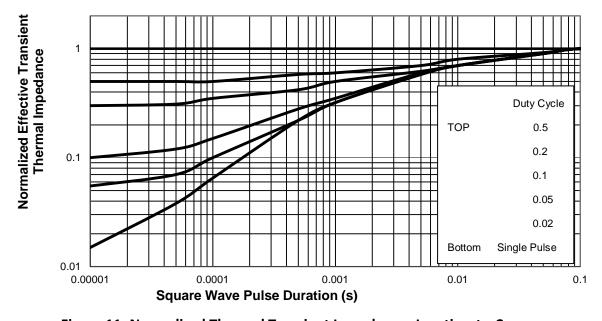


Figure 11: Normalized Thermal Transient Impedance, Junction-to-Case



Version 4.0 6 / 8

3. Marking information

Top Marking Rule

PFC PRM
2R9N10CT
YYWW ABSH

PRM2R9N10CT = Product Type Marking Code

YYWW = Date Code

YY = Last two digits of year

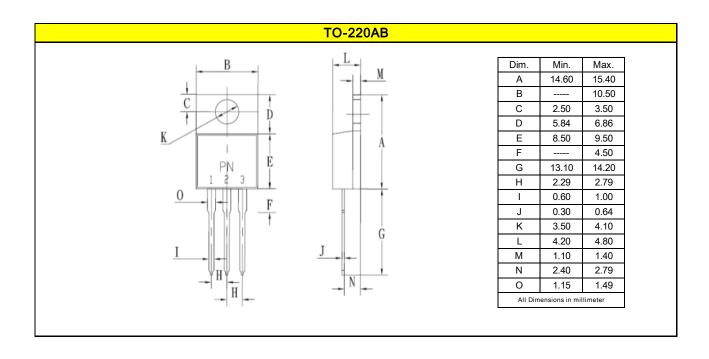
WW = Week code

ABS = Assembly code

H = Halogen Free (N/A = common molding compound)

4. Package information

Package Outline Dimensions millimeters





Version 4.0 7 / 8

5. Ordering information

Part Number	Package	Delivery mode
PRM2R9N10CT	TO-220AB	50 pcs / Tube

Mechanical

Molder Plastic: UL Flammability Classification Rating 94V-0
 Device Weight: 0.07 ounces (1.96grams) - TO-220AB

■ Mounting Torque: Recommended 4~5 kg-cm

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Version 4.0 8 / 8